NRG™ SLE 66R35

Wafer specification

About this document

This document is valid only in combination with the latest version of the general issue of the chip delivery specification for wafer.

Document number: Z8F50253763

Table of contents

About this document . . . 1
Table of contents . . . 2
1 Chip dimensions . . . 3
2 Possible systems on the wafer . . . 3
3 Pad metalization on front . . . 3
4 Passivation . . . 3
5 Bonding area (pad) . . . 3
A Chip layout, Type A . . . 4
Revision history . . . 5
Disclaimer . . . 6

1 Chip dimensions

Location	Lot no	Type		
Dresden	ZA...	A	Stepping size:	0.98 mm x 1.14 mm
			Scribe line:	92 µm / 62 µm
Scribe line without sealring:			According to Chip layout	

2 Possible systems on the wafer

Location	Lot no	Type	Possible systems
Dresden	ZA...	A	25,158

3 Pad metalization on front

Location	Lot no	Type		
Dresden	ZA...	A	Material	AlCu
			Thickness	600 nm ± 50 nm

4 Passivation

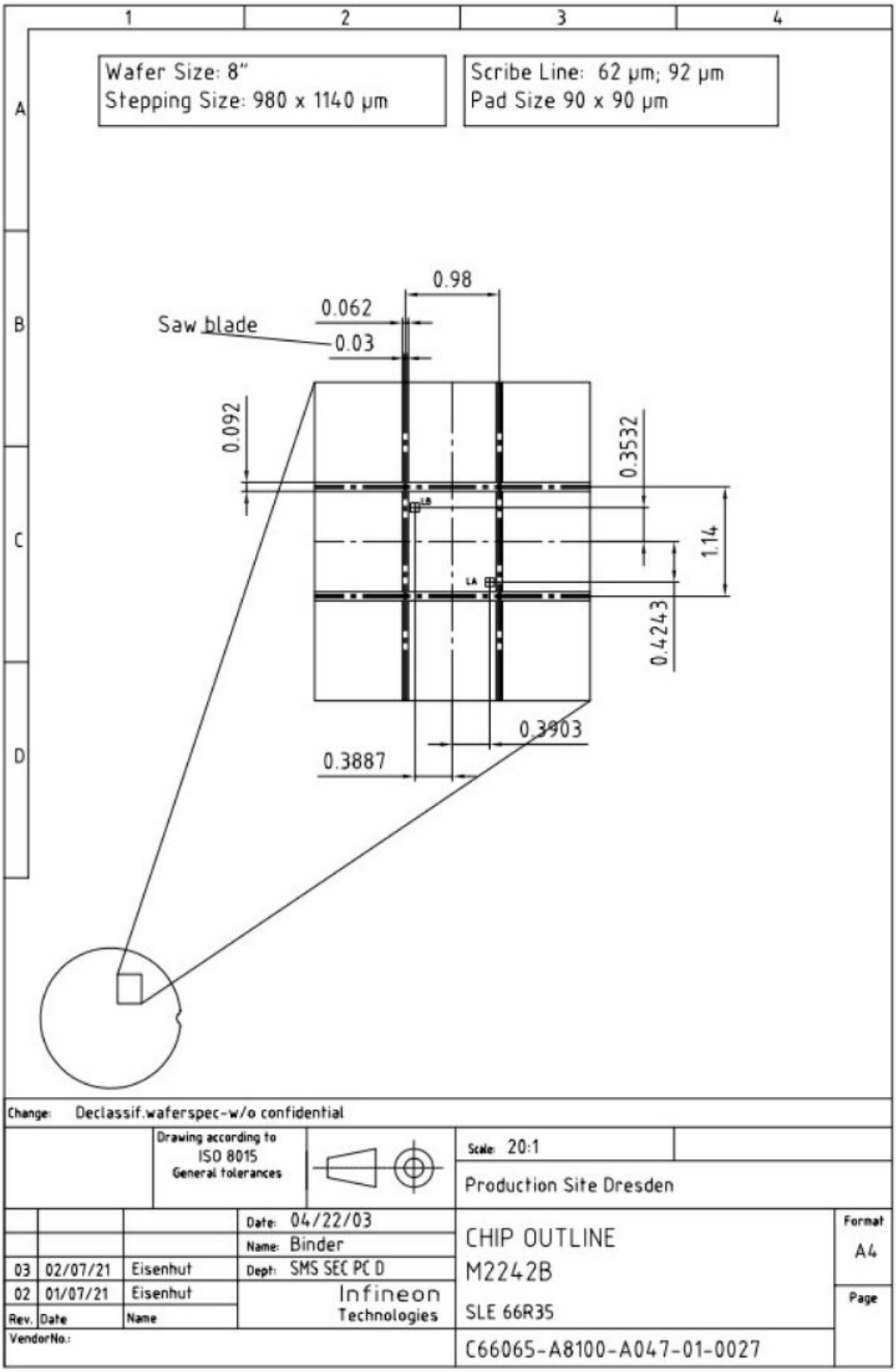
Location	Lot no	Type		
Dresden	ZA...	A	Material:	Thickness:
			Plasmaoxide/ plasmanitride	640 nm ± 60 nm
			Photoimide	2.5 µm ± 0.5 µm

5 Bonding area (pad)

Pad size:	See Chip layout
Bond pad material:	Depends on respective technology, see Pad metalization on front

Recommended condition for die and wire bonding climate: 23°C ± 1K, 30% - 60% relative humidity

A Chip layout, Type A



Revision history

Date	Revision	Change position	Change description
2022-10-11	Revision 3.0	All	Updated editorial changes
2021-05-10	Revision 2.0	All	• Updated document classification • Added Possible systems on the wafer
2011-03	Revision 1.0	All	Initial release

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2022-10-11

Published by

Infineon Technologies AG

81726 Munich, Germany

© 2022 Infineon Technologies AG

All Rights Reserved.

Do you have a question about any aspect of this document?

Email:
CSSCustomerService@infineon.com

Document reference
IFX-eej1665380416851

Important notice

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

Warnings

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.